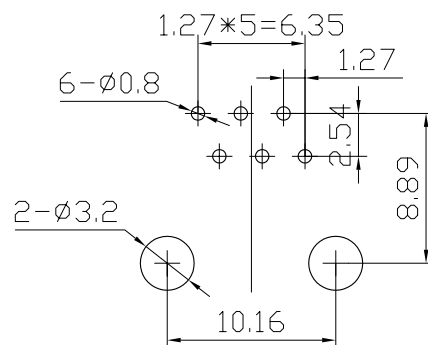
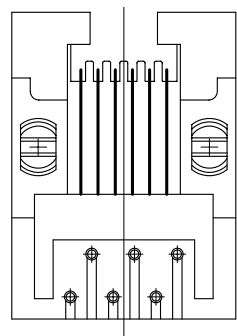
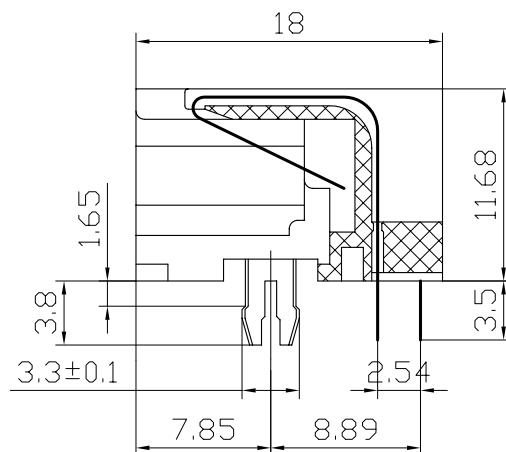
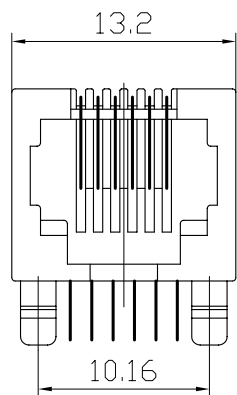




PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
2.CONTACT MATERIAL :PHOSPHOR BRONZE $t=0.35\text{mm}$.
3.PLATING : GOLD PLATING $3\mu\sim 50\mu$ OVER NICKEL

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
2.CURRENT RATING :1.5 AMP.
3.CONTACT RESISTANCE :30 MILLIOHMS MAX.
4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY: :750 CYCLES MIN.
2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1.STORAGE : -40°C TO 85°C.
2.OPERATION : 0°C TO 70°C.



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X" ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: RJ11 90 ° DIP 6P6C	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYCW10-RJ11-180B
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱国夷	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	HYC-RJ16070717
			SHEET NO.	1 OF 1